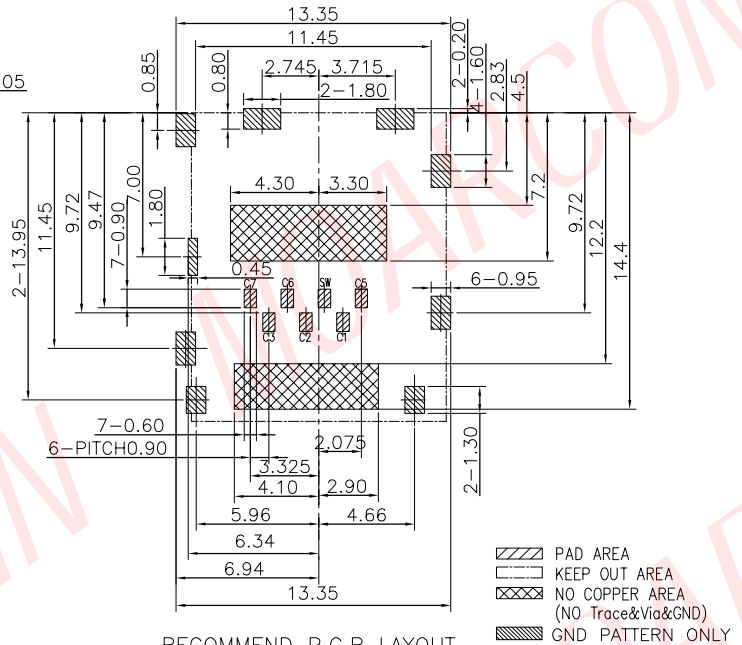
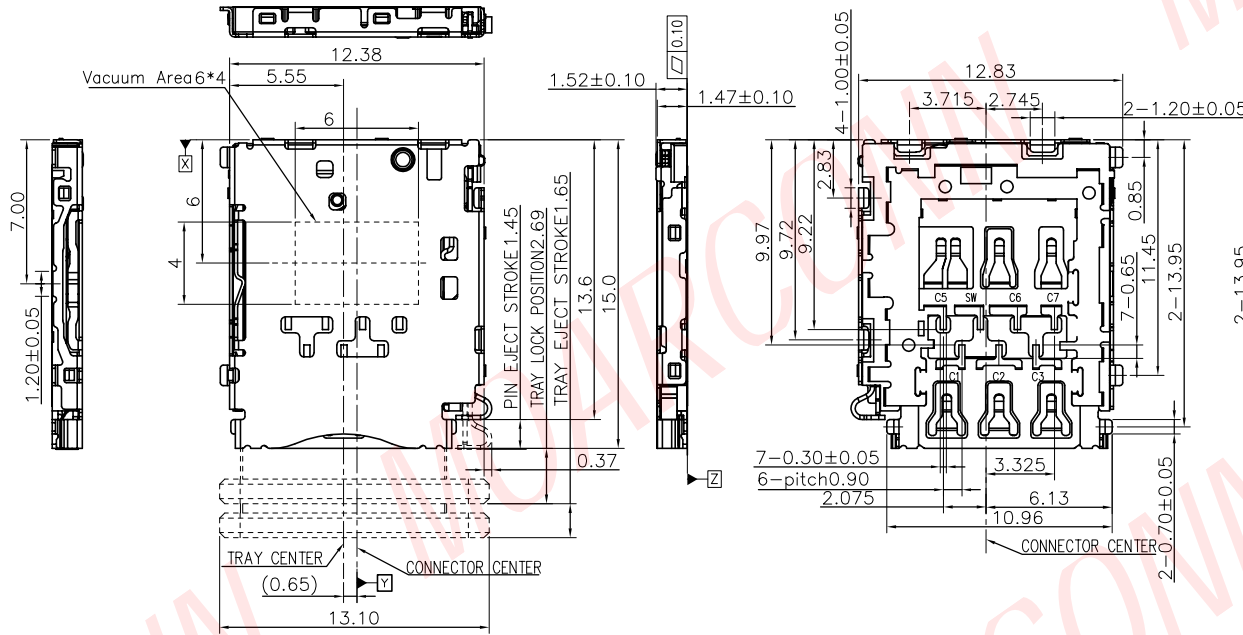
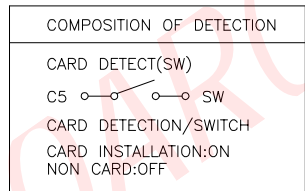
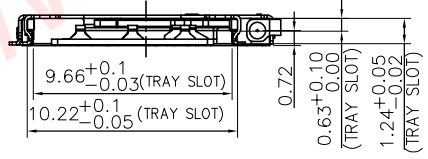


All materials, plating and process meet HF requirements.



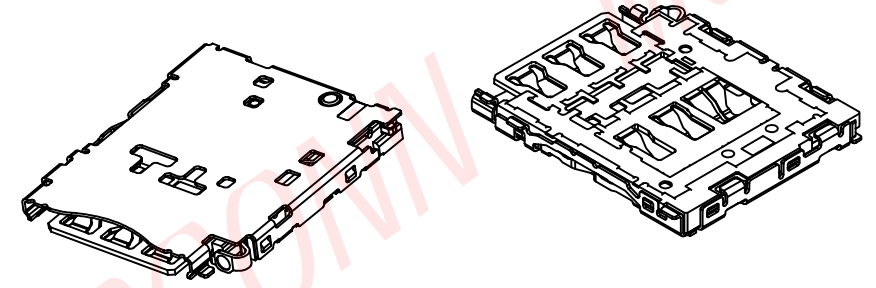
RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



- NOTE:
- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
 - 1-3 Cover: SUS304-H T=0.15±0.03mm
 - Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 30u" Min.
 - Solder area: Gold 0.8u" Min.
 - Specification:
 - 3-1. Current Rating :0.5A max.
 - 3-2. Contact Resistance: 50 mOhms max
 - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
 - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
 - 3-5. Operating Temperature: -40°C to +85°C
 - 3-6. Mating Cycles: 5000 Insertions
 - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
 - Part Must Comply Taisol HF WD-3-I-091 Specification.
 - Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, if Use A Metal Mask Less Than 0.15mm Thick.

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.				
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NANO SIM H1.5 CARD CONNECTOR	DRAWING: Aaron	DATE: 2021.08.28	
DIMENSION TOLERANCE X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'	PRODUCT NO. : NS150-T1131-18	CHECK:	DATE:	DRAWING NO. : D-NS150-T1131-18	APPROVED:	DATE:
	SCALE: 1:1	DWG ID: C D	REV.: B	PAGE: 1 OF 1		

B	-----	Modify the material of shell	Aaron	2021.08.28
A	-----	NEW RELEASE	PURE	2019.07.15
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				